

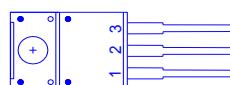
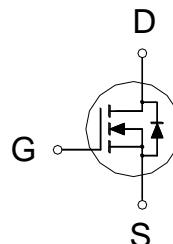
NIKO-SEM
**N-Channel Enhancement Mode
Field Effect Transistor**
PP4B10BF

TO-220F

Halogen-Free & Lead-Free

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
100V	4.4mΩ	78A



1. GATE
2. DRAIN
3. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	100	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	78	A
	$T_C = 100^\circ\text{C}$		55	
Pulsed Drain Current ¹		I_{DM}	230	
Avalanche Current		I_{AS}	17	
Avalanche Energy	$L = 1\text{mH}$	E_{AS}	145	mJ
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	60	W
	$T_C = 100^\circ\text{C}$		30	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 175	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	Steady-State	$R_{\theta JA}$		62.5	°C / W
Junction-to-Case	Steady-State	$R_{\theta JC}$		2.5	

¹Pulse width limited by maximum junction temperature.

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	100			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1	1.7	3	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}$			1	
		$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 55^\circ\text{C}$			10	μA
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		3.7	4.4	
		$V_{\text{GS}} = 4.5\text{V}, I_D = 20\text{A}$		4.7	5.6	$\text{m}\Omega$
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 5\text{V}, I_D = 20\text{A}$		75		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 50\text{V}, f = 1\text{MHz}$		4219		pF
Output Capacitance	C_{oss}			790		
Reverse Transfer Capacitance	C_{rss}			10		
Gate Resistance	R_g	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		1		Ω
Total Gate Charge ²	Q_g	$V_{\text{GS}} = 10\text{V}$		89		nC
				49		
Gate-Source Charge ²	Q_{gs}	$V_{\text{DS}} = 50\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		12		nC
Gate-Drain Charge ²	Q_{gd}			26		
Turn-On Delay Time ²	$t_{\text{d}(\text{on})}$			19		
Rise Time ²	t_r			52		
Turn-Off Delay Time ²	$t_{\text{d}(\text{off})}$	$V_{\text{DS}} = 50\text{V}, I_D \approx 20\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		110		nS
Fall Time ²	t_f			117		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ\text{C}$)						
Continuous Current	I_s				50	A
Forward Voltage ¹	V_{SD}	$I_F = 20\text{A}, V_{\text{GS}} = 0\text{V}$			1.2	V
Reverse Recovery Time	t_{rr}	$I_F = 20\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$		59		nS
Reverse Recovery Charge	Q_{rr}			78		nC

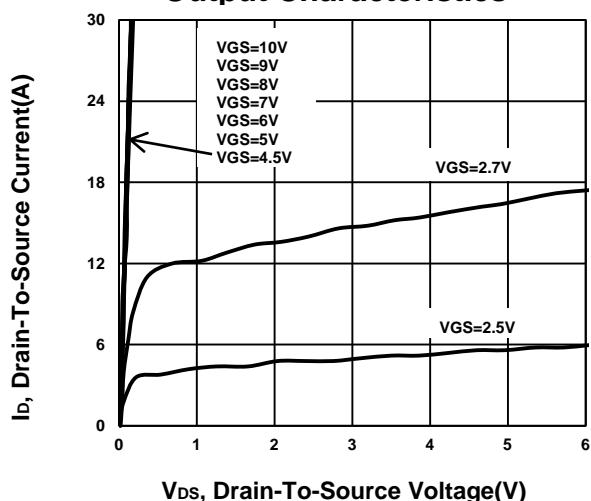
¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.

NIKO-SEM

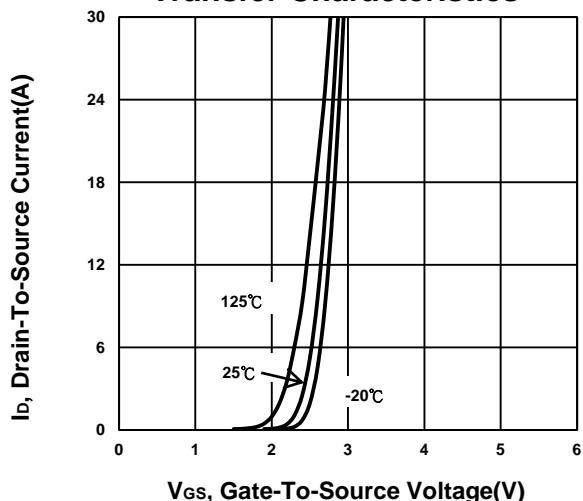
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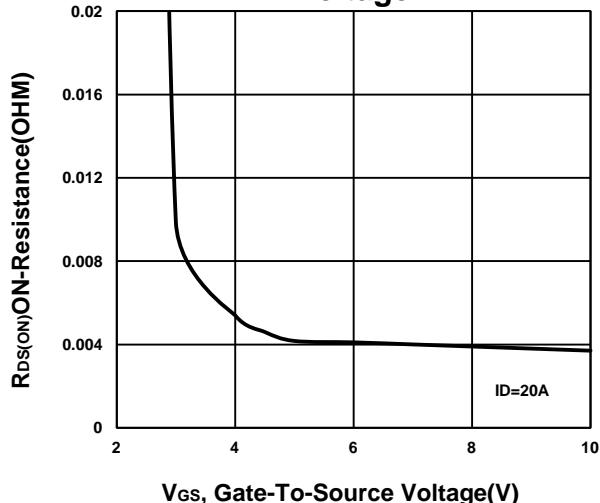
Output Characteristics



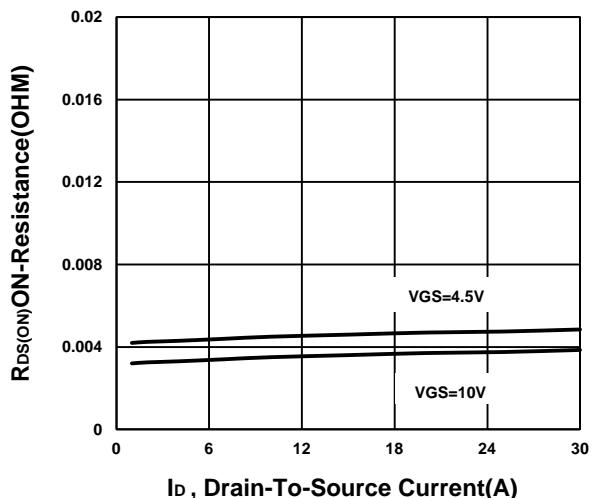
Transfer Characteristics



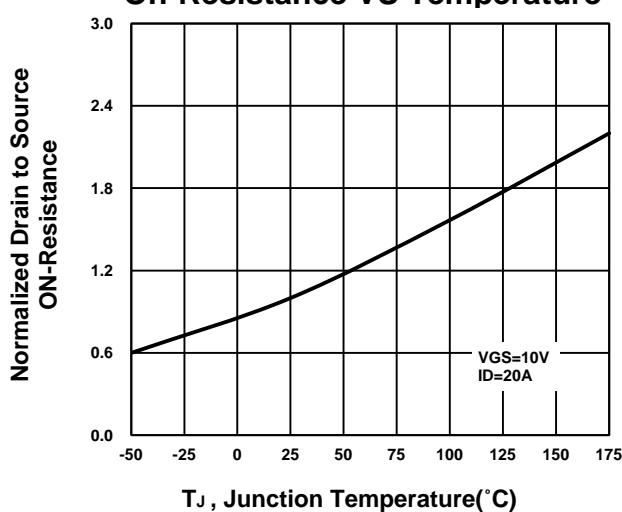
On-Resistance VS Gate-To-Source Voltage



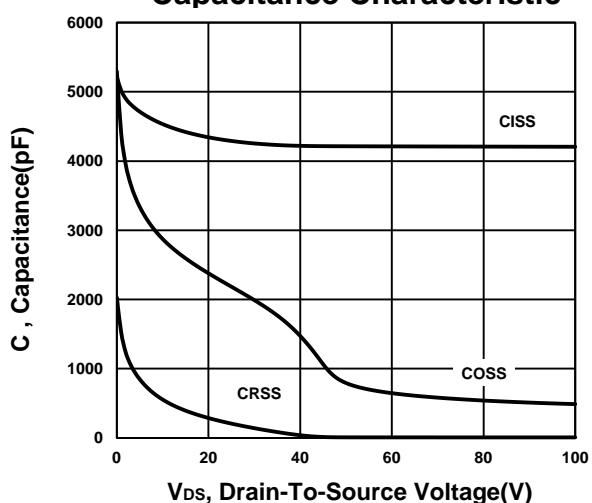
On-Resistance VS Drain Current

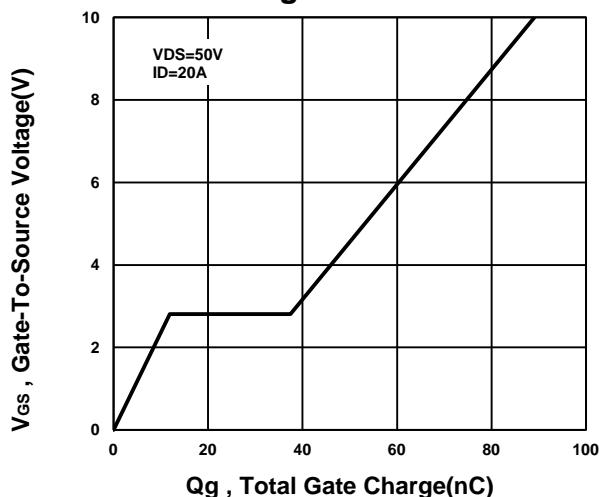
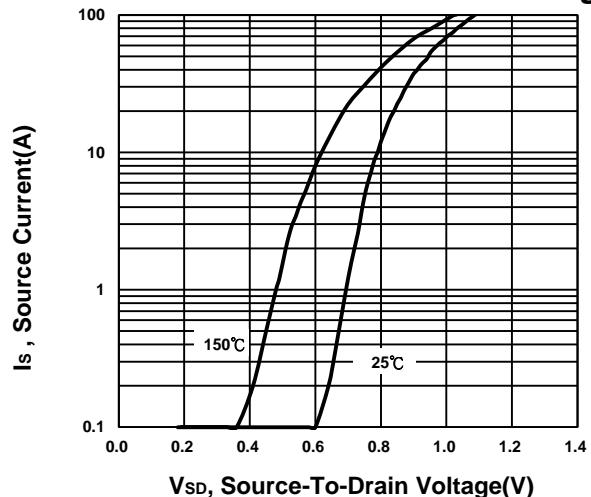
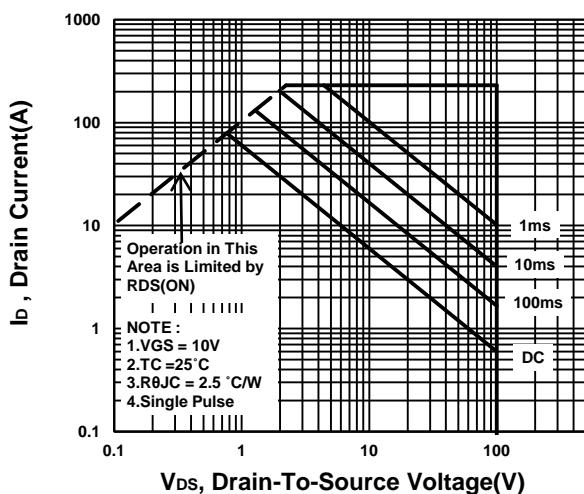
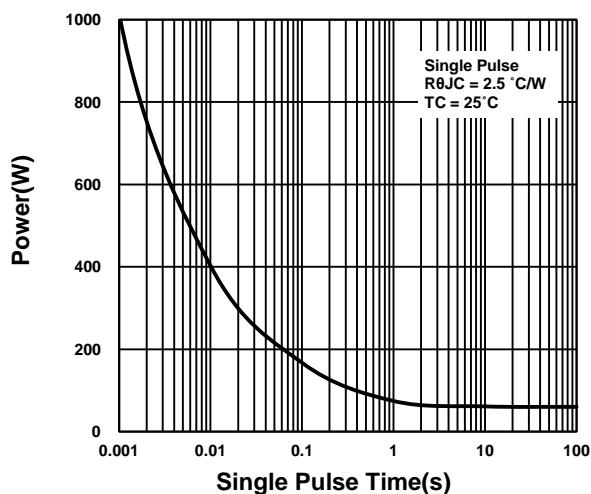


On-Resistance VS Temperature



Capacitance Characteristic



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Gate charge Characteristics**Source-Drain Diode Forward Voltage****Safe Operating Area****Single Pulse Maximum Power Dissipation****Transient Thermal Response Curve**